

Continental Device India Limited

An ISO/TS16949 and ISO 9001 Certified Company



PNP SILICON PLANAR EPITAXIAL TRANSISTORS



BC212, A, B BC213, A, B, C BC214, B, C

TO-92 Plastic Package

Silicon Small Signal General Purpose Amplifier

ABSOLUTE MAXIMUM RATINGS (T_a=25°C unless specified otherwise)

DESCRIPTION	SYMBOL	BC212	BC213	BC214	UNITS
Collector Emitter Voltage	V _{CEO}	50	30	30	V
Collector Base Voltage	V _{CBO}	60	45	45	V
Emitter Base Voltage	V _{EBO}		5		V
Collector Current Continuous	Ι _C		100		mA
Power Dissipation @ T _a =25 ^o C	P _D		350		mW
Derate Above 25°C			2.8		mW/ ⁰C
Power Dissipation @ T _c =25 ^o C	P _D		1		W
Derate Above 25°C			8		mW/ ⁰C
Operating And Storage Junction Temperature Range	T _j , T _{stg}		-55 to +150		°C

THERMAL RESISTANCE

Junction to Ambient in free air	R _{th (j-a)}	357	°C/W
Junction to case	R _{th (j-c)}	125	°C/W



BC212, A, B BC213, A, B, C BC214, B, C

TO-92 Plastic Package

ELECTRICAL CHARACTERISTICS (T_a=25°C unless specified otherwise)

		TEST CONDITION	MINI	TVD			
DESCRIPTION	SYMBOL	TEST CONDITION	MIN	ТҮР	MAX	UNITS	
Collector Emitter Voltage	V_{CEO}	I _C =2mA,I _B =0					
BC212			50			V	
BC213, BC214			30			V	
Collector Base Voltage	V _{CBO}	I _C =10uA.I _E =0					
BC212			60			V	
BC213, BC214			45			V	
Emitter Base Voltage	V _{EBO}	I _E =10uA, I _C =0	5			V	
Collector Cut off Current	I _{CBO}	$V_{CB}=30V,I_{E}=0$			15	nA	
Emitter Cut off Current	I _{EBO}	V_{EB} =4V, I _C =0			15	nA	
DC Current Gain							
BC212, BC213	h _{FE}	I _C =10uA,V _{CE} =5V	40				
BC214			100				
BC212	h _{FE}	I _C =2mA,V _{CE} =5V	60				
BC213			80				
BC214			140		600		
BC212, BC214	h _{FE}	I _C =100mA,V _{CE} =5V*		120			
BC213				140			
Collector Emitter Saturation Voltage	V _{CE(sat)}	I _C =10mA,I _B =0.5mA		0.10		V	
		I _C =100mA,I _B =5mA*		0.25	0.6	V	
Base Emitter Saturation Voltage	V _{BE(sat)}	I _C =100mA,I _B =5mA*		1.00	1.4	V	
Base Emitter On Voltage	$V_{\text{BE(on)}}$	I _C =2mA,V _{CE} =5V	0.6	0.62	0.72	V	

*Pulse Condition: Pulse Width = 300ms, Duty Cycle = 2%.

PNP SILICON PLANAR EPITAXIAL TRANSISTORS



BC212, A, B BC213, A, B, C BC214, B, C

TO-92 Plastic Package

ELECTRICAL CHARACTERISTICS (T_a=25°C unless specified otherwise)

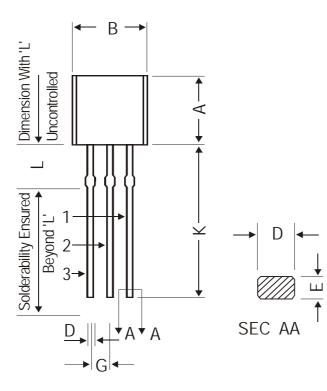
DYNAMICS CHARACTERISTICS

DESCRIPTION	SYMBOL	TEST CONDITION	MIN	ТҮР	MAX	UNITS
Transition Frequency						
BC212	f _T	I _C =10mA, V _{CE} =5V		280		MHz
BC213		f=50MHz		360		MHz
BC214				320		MHz
Output Capacitance	C _{ob}	V _{CB} =10V, I _E =0			6	рF
Noise Figure						
BC212, BC213	NF	I_{C} =200uA, V_{CE} =5V			10	dB
		$R_s=2K\Omega f=1KHz$				
		f=200Hz				
BC214	NF	I_C =200uA, V_{CE} =5V			2	dB
		$R_s=2K\Omega f=30Hz$				
		to 15KHz				
Small Signal Current Gain						
BC212	h _{fe}	I_{C} =2mA, V_{CE} =5V	60			
BC213		f=1KH _Z	80			
BC214			140			
BC212A, BC213A	h _{fe}	I _C =2mA, V _{CE} =5V	100		300	
BC212B, BC213B, BC214B		f=1KH _z	200		400	
BC213C, BC214C			350		600	

*Pulse Condition: Pulse Width = 300ms, Duty Cycle = 2%.

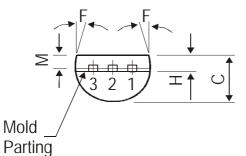
BC212, A, B BC213, A, B, C BC214, B, C

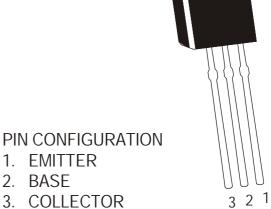
TO-92 Plastic Package



DIM	MIN.	MAX.
А	4.32	5.33
В	4.45	5.20
С	3.18	4.19
D	0.41	0.55
E	0.35	0.50
F	5 D	EG
G	1.14	1.40
Н	1.20	1.40
К	12.70	
N	12.70	
L	1.982	2.082

All dimensions are in mm





1. EMITTER

2. BASE

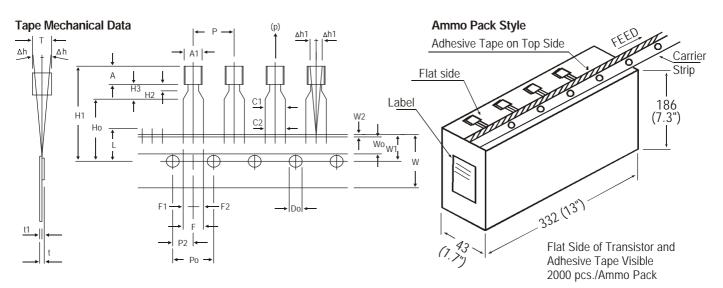
The TO-92 Package, Tape and Ammo Pack drawings are correct as on the date of issue/revision of this Data Sheet. The currently valild dimensions and information, may please be confirmed from the TO-92 Drawing in the Packages and Packing Section of the Product Catalogue.

Packing Details

Line

PACKAGE	STANDARDPACK		INNER CARTON BOX		OUTER CARTON BOX		
	Details	Net Weight/Qty	Size	Qty	Size	Qty	Gr Wt
TO-92 Bulk	1K/polybag	200 gm/1K pcs	3" x 7.5" x 7.5"	5K	17" x 15" x 13.5"	80K	23 kgs
TO-92 T&A	2K/ammo box	645 gm/2K pcs	12.5" x 8" x 1.8"	2K	17" x 15" x 13.5"	32K	12.5 kgs

TO-92 Tape and Ammo Pack



All dimensions are in mm

BODY THICKNESST3.94.2leads will not to be greater than 0.2mmPITCH OF COMPONENTP12.7 \pm 1.01.02. Maximum non-cumulative variation between tape feed holes shall not exceed 1 mm in 20 pitches.*1FEED HOLE CENTRE TO COMPONENT CENTREP26.35 \pm 0.43. Holddown tape will not exceed beyond the edge(s) of carrier tape and there shall be no exposure of adhesive.*3 COMPONENT ALIGNMENT SIDE VIEW TAPE WIDTH Δh 01.04. There will be no more than three (3) consecutive missing components in a tape.*4 COMPONENT ALIGNMENT FRONT VIEW HOLD-DOWN TAPE WIDTH Δh 01.04. There will be no more than three (3) consecutive missing components in a tape.HOLD-DOWN TAPE WIDTH HOLE POSITIONW20.5 \pm 0.25. A tape trailer, having at least three feed holes.HOLD-DOWN TAPE POSITION LEAD WIRE CLINCH HEIGHTW20.5 \pm 0.25. A tape trailer, having at least three feed holes.MOLD-DOWN TAPE POSITION LEAD WIRE CLINCH HEIGHTL11.04 \pm 0.25. Splices should not interfere with the sprocket feed holes.*5 TOTAL TAPE THICKNESS LEAD - TO - LEAD DISTANCEF1, F22.54 \pm 0.4*1 Cumulative pitch error 1.0 mm/20 pitch*5 TAND OFFH20.451.45*1 Cumulative pitch error 1.0 mm/20 pitch			SPECIFICATION		ON		
BOOV HEIGHTA4.85.21Maximum alignment deviation between leads will not to be greater than 0.2mmBODY THICKNESST3.94.21Maximum alignment deviation between leads will not to be greater than 0.2mm*1FEED HOLE PITCHPo12.7 \pm 0.32Maximum non-cumulative variation between tape feed holes shall not exceed 1 mm in 20 pitches.*2FEED HOLE CENTRE TO COMPONENT CENTREP26.35 \pm 0.43Holddown tape will not exceed beyond the edge(s) of carrier tape and there shall be no exposure of adhesive.*3 COMPONENT ALIGNMENT SIDE VIEW *4 COMPONENT ALIGNMENT FRONT VIEW HOLD-DOWN TAPE WIDTH Δ h01.03HOLD-DOWN TAPE WIDTH HOLD-DOWN TAPE POSITION LEAD WIRE CLINCH HEIGHT COMPONENT HEIGHTW20.5 \pm 0.25HOLD-DOWN TAPE POSITION LEAD VIRE CLINCH HEIGHT LENGTH OF SNIPPED LEADSW20.5 \pm 0.25FEED HOLE DIAMETER LEAD - TO - LEAD DISTANCEDo4 \pm 0.2 \pm 0.4*1 Cumulative pitch error 1.0 mm/20 pitch *2 To be measured at bottom of clinch*TARE STAND OFFH20.451.45 \pm 0.4*1 Cumulative pitch error 1.0 mm/20 pitch *2 To be measured at bottom of clinch	IIEM	SYMBOL	MIN.	NOM.	MAX.	TOL.	
BODY THICKNESST3.94.21. Maximum angine in deviation between leads will not to be greater than 0.2mmPITCH OF COMPONENTP12.7 \pm 1.02. Maximum non-cumulative variation between tape feed holes shall not exceed 1 mm in 20 pitches.*1 FEED HOLE PITCHPo12.7 \pm 0.32. Maximum non-cumulative variation between tape feed holes shall not exceed 1 mm in 20 pitches.*2 FEED HOLE CENTRE TO COMPONENT ALIGNMENT SIDE VIEWP26.35 \pm 0.43. Holddown tape will not exceed beyond the edge(s) of carrier tape and there shall be no exposure of adhesive.*3 COMPONENT ALIGNMENT SIDE VIEW *4 COMPONENT ALIGNMENT FRONT VIEW HOLD-DOWN TAPE WIDTH HOLE POSITION Δh 01.0*4 COMPONENT ALIGNMENT FRONT VIEW HOLE POSITION Δh 01.0.HOLD-DOWN TAPE WIDTH HOLE POSITIONW20.5 \pm 0.2.HOLD-DOWN TAPE POSITION LEAD WIRE CLINCH HEIGHT LENGTH OF SNIPPED LEADSW11.0.FEED HOLE DIAMETER LEAD - TO - LEAD DISTANCEW20.5 \pm 0.2*5 TOTAL TAPE THICKNESS LEAD - TO - LEAD DISTANCEF1, F22.54 \pm 0.4*1 ELAG + TO - LEAD DISTANCEF1, F22.54 \pm 0.4*1 Cumulative pitch error 1.0 mm/20 pitch*2 To be measured at bottom of clinch	BODY WIDTH	A1	4.0		4.8		NOTES
PITCH OF COMPONENTP12.7± 1.02. Maximum non-curulative variation between tape feed holes shall not exceed 1 mm in 20 pitches.*1FEED HOLE CENTRE TO COMPONENT CENTREP26.35± 0.43. Holddown tape will not exceed beyond the edge(s) of carrier tape and there shall be no exposure of adhesive.DISTANCE BETWEEN OUTER LEADSF5.08± 0.43. Holddown tape will not exceed beyond the edge(s) of carrier tape and there shall be no exposure of adhesive.*3 COMPONENT ALIGNMENT SIDE VIEW *4 COMPONENT ALIGNMENT FRONT VIEW TAPE WIDTH $\Delta h1$ 01.0TAPE WIDTH HOLD-DOWN TAPE WIDTH HOLD-DOWN TAPE POSITION LEAD WIRE CLINCH HEIGHT LEAD WIRE CLINCH HEIGHT LEAD WIRE CLINCH HEIGHT LEAD TO - LEAD DISTANCEW20.5± 0.2HOLD-DOWN TAPE POSITION FEED HOLE DIAMETERW20.5± 0.25. A tape trailer, having at least three feed holes are provided after the last component in a tape.HOLD-DOWN TAPE POSITION LEAD WIRE CLINCH HEIGHT LEAD TO - LEAD DISTANCEW20.5± 0.2*5 TOTAL TAPE THICKNESS LEAD - TO - LEAD DISTANCET11.0± 0.2*5 TOTAL TAPE THICKNESS LEAD - TO - LEAD DISTANCEF1, F22.54+ 0.4 - 0.1*1 Cumulative pitch error 1.0 mm/20 pitch*2 STAND OFFH20.451.45*1 Cumulative pitch error 1.0 mm/20 pitch	BODY HEIGHT	А	4.8		5.2		1. Maximum alignment deviation between
*1 FED HOLE PITCHPo12.7 \pm 0.32. Maillin indicative virtuality*2 FEED HOLE CENTRE TO COMPONENT CENTREP2 6.35 \pm 0.4 \pm 0.3between tape feed holes shall not exceed 1 mm in 20 pitches.DISTANCE BETWEEN OUTER LEADSF 5.08 \pm 0.4 \pm 0.6 -0.2 $3.$ Holddown tape will not exceed beyond the edge(s) of carrier tape and there shall be no exposure of adhesive.*3 COMPONENT ALIGNMENT SIDE VIEW *4 COMPONENT ALIGNMENT FRONT VIEW TAPE WIDTH Δh 0 1.0 $4.$ HOLD-DOWN TAPE WIDTH HOLE POSITIONW Ah 0 1.0 $4.$ HOLD-DOWN TAPE POSITION LEAD WIRE CLINCH HEIGHT COMPONENT HEIGHTW2 0.5 \pm 0.2 \pm 0.5HOLD-DOWN TAPE POSITION LEAD WIRE CLINCH HEIGHT LEAD WIRE CLINCH HEIGHT LEAD TO - LEAD DISTANCEW2 0.5 \pm 0.2 \pm 0.5FEED HOLE DIAMETER LEAD - TO - LEAD DISTANCEDo 4 \pm 0.2 \pm 0.2 \pm 0.4*5 TOTAL TAPE THICKNESS LEAD - TO - LEAD DISTANCEF1, F2 2.54 \pm 0.4 -0.1 $*^1$ Cumulative pitch error 1.0 mm/20 pitch $*^2$ To be measured at bottom of clinch	BODY THICKNESS	Т	3.9		4.2		leads will not to be greater than 0.2mm.
*2 FEED HOLE CENTRE TO COMPONENT CENTREP2 6.35 ± 0.4 $= exceed 1 mm in 20 pitches.$ DISTANCE BETWEEN OUTER LEADSF 5.08 ± 0.4 $= 0.6$ $= 0.2$ $= 0.66$ *3 COMPONENT ALIGNMENT SIDE VIEW *4 COMPONENT ALIGNMENT FRONT VIEW TAPE WIDTH Δh 0 1.0 $= 0.2$ $= 0.24$ *4 COMPONENT ALIGNMENT FRONT VIEW TAPE WIDTH Δh 0 1.0 $= 0.22$ $= 0.22$ $= 0.26$ HOLD-DOWN TAPE WIDTH HOLE POSITION LEAD WIRE CLINCH HEIGHT LENGTH OF SNIPPED LEADSW2 0.5 ± 0.2 $= 0.55$ $= 0.22$ *5 TOTAL TAPE THICKNESS t 11.0 $= 0.22$ $= 0.22$ $= 0.22$ $= 0.22$ *5 TOTAL TAPE THICKNESS t 11.0 $= 0.22$ $= 0.22$ $= 0.22$ *1 COMPONENT HEIGHT LEAD - TO - LEAD DISTANCE E E 1.2 $= 0.22$ *1 COMPORENT HEIGHT LEAD - TO - LEAD DISTANCE E E 1.2 $= 0.42$ *1 COMPORENT HEIGHT LEAD - TO - LEAD DISTANCE E E 1.45 $= 0.1$ *1 Comport E E E E $= 0.45$ $= 0.45$ $= 0.45$ *1 Cumulative pitch error 1.0 mm/20 pitch $= 2.54$ $= 0.45$ $= 0.45$ $= 0.45$ *1 Cumulative pitch error 1.0 mm/20 pitch $= 2.54$ $= 0.45$ $= 0.45$ $= 0.45$ *1 Cumulative pitch error 1.0 mm/20 pitch $= 2.54$ $= 0.45$ $= 0.45$ $= 0.45$ *1 Cumulative pitch error 1.0 mm/20 pitch<		Р		12.7		± 1.0	2. Maximum non-cumulative variation
COMPONENT CENTREP2 6.35 ± 0.4 $3.$ Holddown tape will not exceed beyond the edge(s) of carrier tape and there shall be no exposure of adhesive.*3 COMPONENT ALIGNMENT SIDE VIEW Δh 0 1.0 $*0.6$ 0.2 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5 0.5	* ¹ FEED HOLE PITCH	Po		12.7		± 0.3	
DISTANCE BETWEEN OUTER LEADSF5.081.0.43. Holdadown tape will not exceed beyond the edge(s) of carrier tape and there shall be no exposure of adhesive.*3 COMPONENT ALIGNMENT SIDE VIEW *4 COMPONENT ALIGNMENT FRONT VIEW TAPE WIDTH $\triangle h$ 01.04. There will be no more than three (3) consecutive missing components in a tape.HOLD-DOWN TAPE WIDTH HOLD-DOWN TAPE WIDTHW18 ± 0.5 ± 0.2 5. A tape trailer, having at least three feed holes are provided after the last component in a tape.HOLD-DOWN TAPE POSITION LEAD WIRE CLINCH HEIGHT LENGTH OF SNIPPED LEADS LEAD - TO - LEAD DISTANCEW20.5 ± 0.2 5. A tape trailer, having at least three feed holes are provided after the last component in a tape.*5 TOTAL TAPE THICKNESS LEAD - TO - LEAD DISTANCEH110 ± 0.2 8. Holdadown tape will not exceed beyond the edge(s) of carrier tape and there shall be no exposure of adhesive.*1 Cumulative pitch error 1.0 mm/20 pitch*2 To be measured at bottom of clinch	² FEED HOLE CENTRE TO						exceed 1 mm in 20 pitches.
LEADSF 5.08 $\frac{1}{2}, 0.2$ shall be no exposure of adhesive.*3 COMPONENT ALIGNMENT SIDE VIEW *4 COMPONENT ALIGNMENT FRONT VIEW TAPE WIDTH Δh 01.0.4*4 COMPONENT ALIGNMENT FRONT VIEW TAPE WIDTH Δh 01.3.5HOLD-DOWN TAPE WIDTH HOLE POSITIONW18 ± 0.5 .5HOLD-DOWN TAPE POSITION LEAD WIRE CLINCH HEIGHT COMPONENT HEIGHTW20.5 ± 0.2 .6HOLD-DOWN TAPE POSITION LEAD WIRE CLINCH HEIGHT LENGTH OF SNIPPED LEADSW20.5 ± 0.2 .6*5 TOTAL TAPE THICKNESS LEAD - TO - LEAD DISTANCET23.25.6.7STAND OFFH20.451.45*1.45	COMPONENT CENTRE	P2		6.35		± 0.4	
*3 COMPONENT ALIGNMENT SIDE VIEW *4 COMPONENT ALIGNMENT FRONT VIEW TAPE WIDTH $\triangle h$ 0 1.0 4 . There will be no more than three (3) consecutive missing components in a tape.HOLD-DOWN TAPE WIDTH HOLE POSITIONW0 6 ± 0.5 ± 0.5 5 . A tape trailer, having at least three feed holes are provided after the last component in a tape.HOLD-DOWN TAPE POSITION LEAD WIRE CLINCH HEIGHT LENGTH OF SNIPPED LEADSW2 0.5 ± 0.2 5 . A tape trailer, having at least three feed holes are provided after the last component in a tape.FEED HOLE DIAMETER * TOTAL TAPE THICKNESSL11.0 5 . Splices should not interfere with the sprocket feed holes.*5 TOTAL TAPE THICKNESSt1.2 1.45 $*1$ Cumulative pitch error 1.0 mm/20 pitchSTAND OFFH2 0.45 1.45 $*2$ To be measured at bottom of clinch				E 00		+ 0.6	
*4 COMPONENT ALIGNMENT FRONT VIEW TAPE WIDTH $\Delta h1$ 01.3consecutive missing components in a tape.HOLD-DOWN TAPE WIDTHW18 ± 0.5 $5 \cdot 0.2$ $5 \cdot 0.2$ $5 \cdot 0.5$ $5 \cdot 0.2$ $5 \cdot 0.5$ $5 \cdot 0$		F		0.08		- 0.2	
TAPE WIDTHW18± 0.5tape.HOLD-DOWN TAPE WIDTHWo6± 0.2+ 0.7HOLD-DOWN TAPE POSITIONW19+ 0.7- 0.5HOLD-DOWN TAPE POSITIONW20.5± 0.2+ 0.7LEAD WIRE CLINCH HEIGHTHo16± 0.5COMPONENT HEIGHTH123.25-LENGTH OF SNIPPED LEADSL11.0FEED HOLE DIAMETERDo4± 0.2*5 TOTAL TAPE THICKNESSt1.2LEAD - TO - LEAD DISTANCEF1, F22.54+ 0.4STAND OFFH20.451.45	* ³ COMPONENT ALIGNMENT SIDE VIEW	∆h		0	1.0		
TAPE WIDTHW18± 0.3HOLD-DOWN TAPE WIDTHWo6± 0.2HOLE POSITIONW19+ 0.7U9+ 0.7- 0.5± 0.2HOLD-DOWN TAPE POSITIONW20.5± 0.2LEAD WIRE CLINCH HEIGHTHo16± 0.5COMPONENT HEIGHTH123.25LENGTH OF SNIPPED LEADSL11.0FEED HOLE DIAMETERDo4± 0.2*5 TOTAL TAPE THICKNESSt1.2LEAD - TO - LEAD DISTANCEF1, F22.54+ 0.4STAND OFFH20.451.45	*4 COMPONENT ALIGNMENT FRONT VIEW	\triangle h1		0	1.3		
HOLD DOWNT HILD WIDTHWI9+ 0.7 - 0.5holes are provided after the last component in a tape.HOLD-DOWN TAPE POSITIONW20.5± 0.2holes are provided after the last component in a tape.HOLD-DOWN TAPE POSITIONW20.5± 0.26. Splices should not interfere with the sprocket feed holes.LEAD WIRE CLINCH HEIGHTH016± 0.56. Splices should not interfere with the sprocket feed holes.COMPONENT HEIGHTH123.2511.06. Splices should not interfere with the sprocket feed holes.FEED HOLE DIAMETERDo4± 0.211.0*5 TOTAL TAPE THICKNESSt1.2* 0.4* 1.2LEAD - TO - LEAD DISTANCEF1, F22.54+ 0.4* 0.1STAND OFFH20.451.45* 0.1*2	TAPE WIDTH	W		18		± 0.5	
HOLE POSITIONW1Y+ 0.7 - 0.5component in a tape.HOLD-DOWN TAPE POSITIONW20.5± 0.26. Splices should not interfere with the sprocket feed holes.LEAD WIRE CLINCH HEIGHTH016± 0.56. Splices should not interfere with the sprocket feed holes.COMPONENT HEIGHTH123.25± 0.56. Splices should not interfere with the sprocket feed holes.LENGTH OF SNIPPED LEADSL11.0FEED HOLE DIAMETERPool*5 TOTAL TAPE THICKNESSt1.2* 0.2* 1.2LEAD - TO - LEAD DISTANCEF1, F22.54+ 0.4* 0.1STAND OFFH20.451.45* 1 cumulative pitch error 1.0 mm/20 pitch	HOLD-DOWN TAPE WIDTH	Wo		6		± 0.2	
HOLD-DOWN TAPE POSITION LEAD WIRE CLINCH HEIGHTW2 Ho 0.5 16 ± 0.2 ± 0.5 6 . Splices should not interfere with the sprocket feed holes.COMPONENT HEIGHTH1 23.25 ± 0.5 6 . Splices should not interfere with the sprocket feed holes.LENGTH OF SNIPPED LEADSL11.0 ± 0.2 ± 0.2 FEED HOLE DIAMETERDo4 ± 0.2 ± 0.2 *5 TOTAL TAPE THICKNESSt1.2 ± 0.4 ± 0.4 LEAD - TO - LEAD DISTANCEF1, F2 2.54 ± 0.4 ± 0.4 STAND OFFH2 0.45 1.45 ± 0.4 ± 2	HOLE POSITION	W1		9			
Indeb-bown TAPE POSITIONW20.3± 0.2sprocket feed holes.LEAD WIRE CLINCH HEIGHTHo16± 0.5sprocket feed holes.COMPONENT HEIGHTH123.2511.0sprocket feed holes.LENGTH OF SNIPPED LEADSL11.011.0sprocket feed holes.FEED HOLE DIAMETERDo4± 0.2sprocket feed holes.*5 TOTAL TAPE THICKNESSt1.2*1 Cumulative pitch error 1.0 mm/20 pitchLEAD - TO - LEAD DISTANCEF1, F22.54+ 0.4STAND OFFH20.451.45						- 0.5	
LEAD WIRE CLINCH HEIGHTHo16± 0.5COMPONENT HEIGHTH123.25LENGTH OF SNIPPED LEADSL11.0FEED HOLE DIAMETERDo4± 0.2*5 TOTAL TAPE THICKNESSt1.2LEAD - TO - LEAD DISTANCEF1, F22.54+ 0.4STAND OFFH20.451.45	HOLD-DOWN TAPE POSITION	W2		0.5			
LENGTH OF SNIPPED LEADS L 11.0 *0.2 REMARKS *5 TOTAL TAPE THICKNESS t 1.2 *0.4 *1.2 LEAD - TO - LEAD DISTANCE F1, F2 2.54 *0.4 *1 Cumulative pitch error 1.0 mm/20 pitch STAND OFF H2 0.45 1.45 1.45 *2 To be measured at bottom of clinch	LEAD WIRE CLINCH HEIGHT	Ho		16		± 0.5	sprocket reed holes.
FEED HOLE DIAMETERDo4± 0.2REMARKS*5 TOTAL TAPE THICKNESSt1.2+ 0.4*1 Cumulative pitch error 1.0 mm/20 pitchLEAD - TO - LEAD DISTANCEF1, F22.54+ 0.4*1 Cumulative pitch error 1.0 mm/20 pitchSTAND OFFH20.451.45*2 To be measured at bottom of clinch	COMPONENT HEIGHT	H1			23.25		
*5 TOTAL TAPE THICKNESS t 1.2 *1 Cumulative pitch error 1.0 mm/20 pitch LEAD - TO - LEAD DISTANCE F1, F2 2.54 + 0.4 - 0.1 *2 To be measured at bottom of clinch STAND OFF H2 0.45 1.45 - 0.1 *2 To be measured at bottom of clinch	LENGTH OF SNIPPED LEADS	L			11.0		
LEAD - TO - LEAD DISTANCE F1, F2 2.54 + 0.4 *1 Cumulative pitch error 1.0 mm/20 pitch STAND OFF H2 0.45 1.45 *2 To be measured at bottom of clinch		Do		4		± 0.2	REMARKS
STAND OFF H2 0.45 1.45 *2 To be measured at bottom of clinch	*5 TOTAL TAPE THICKNESS	L L			1.2		*1 Cumulative nitch error 1.0 mm/20 nitch
STAND OFF H2 0.45 1.45	LEAD - TO - LEAD DISTANCE	F1, F2		2.54			
	STAND OFF	H2	0.45		1.45	- U. I	
CLINCH HEIGHT H3 3.0 *3 At top of body	CLINCH HEIGHT	H3			3.0		*3 At top of body
LEAD PARALLELISM C1 - C2 0.22 *4 At top of body	LEAD PARALLELISM	C1 - C2			0.22		*4 At top of body
PULL - OUT FORCE (p) 6N *5 t1 0.3 – 0.6 mm	PULL - OUT FORCE		6N				*5 t1 0.3 – 0.6 mm

BC212, A, B BC213, A, B, C BC214, B, C

TO-92 Plastic Package

Disclaimer

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